

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL03C0R6BA3GNNC
- Description : CAP, 0.6pF, 25V, ±0.1pF, C0G, 0201

A. Samsung Part Number

			<u>CL</u> ①	<mark>03</mark> ②	<u>C</u> 3	<u>0R6</u> ④	<u>B</u> 5	<u>A</u> 6	<u>3</u> ⑦	<u>G</u> ⑧	<u>N</u> 9	<u>N</u> 10	<u>C</u> 11			
			U	U	U	G	U	U	U	۲	٢		U			
1	Series	Samsung	Multi-la	yer C	eram	nic Cap	acito	or								
2	Size	0201	(inch co	ode)		L:	0.6	± 0.0	3	mm		W:	0.3	± 0.03	mm	
3	Dielectric	C0G					8	Inne	r ele	ctroc	le		Cu			
4	Capacitance	0.6	рF					Tern	ninat	ion			Cu			
5	Capacitance	±0.1	рF					Plati	ng				Sn 10	00%	(Pb Fre	e)
	tolerance						9	Proc	luct				Norm	al		
6	Rated Voltage	25	V				10	Spee	cial				Rese	rved for	future us	se
\bigcirc	Thickness	0.3	± 0.03	mm			1	Pack	agir	ng			Card	board Ty	vpe, 7" re	el

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1M±±10% 0.5~5Vrms					
Q	412 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 °C to 125 °C, Capacitance change	shoud be within ±30PPM/℃)					
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder					
	is to be soldered newly	235±5℃, 5±0.5sec.					
		2) SnAg3.0Cu0.5 solder					
		245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)				
Humidity	Capacitance change :	40±2℃, 90~95%RH, 500+12/-0hrs				
	within $\pm 5\%$ or ± 0.5 pF whichever is larger					
	Q: 206 min					
	IR : 1000Mohm or 50Mohm · μF					
	Whichever is Smaller					
Moisture	Capacitance change :	With rated voltage				
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q : 102 min					
	IR : 500Mohm or 25Mohm $\cdot \mu F$					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature				
	Q : 206 min	1000+48/-0hrs				
	IR : 1000Mohm or 50Mohm · μF					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Min. operating temperatur(\rightarrow 25 °C				
	Tan δ, IR : initial spec.	ightarrow Max. operating temperature $ ightarrow$ 25 °C				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\!\mathrm{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.